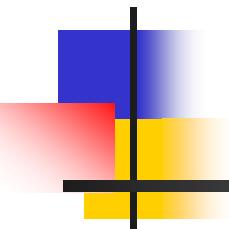
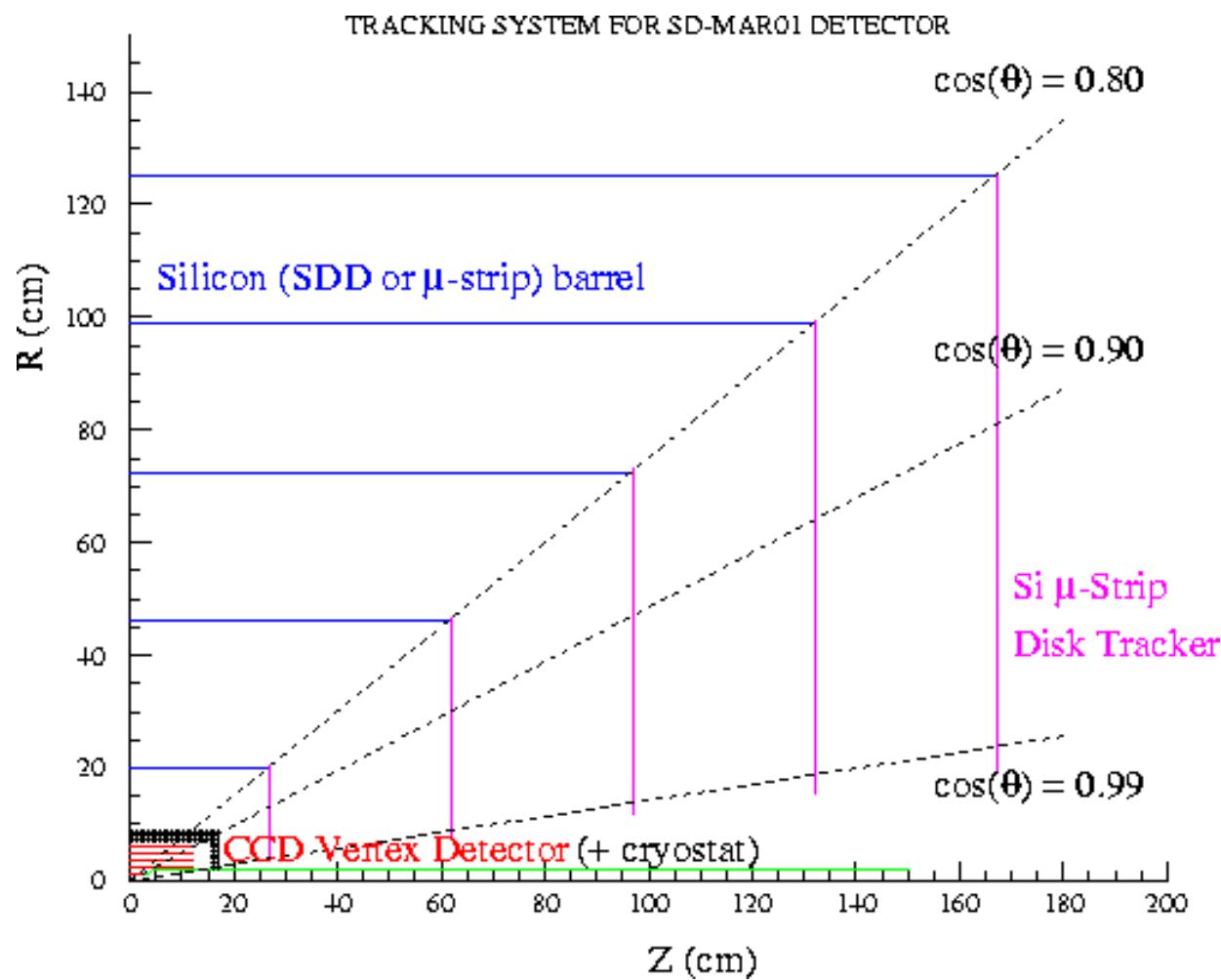


Progress towards a Long Shaping-Time Readout for Silicon Strips

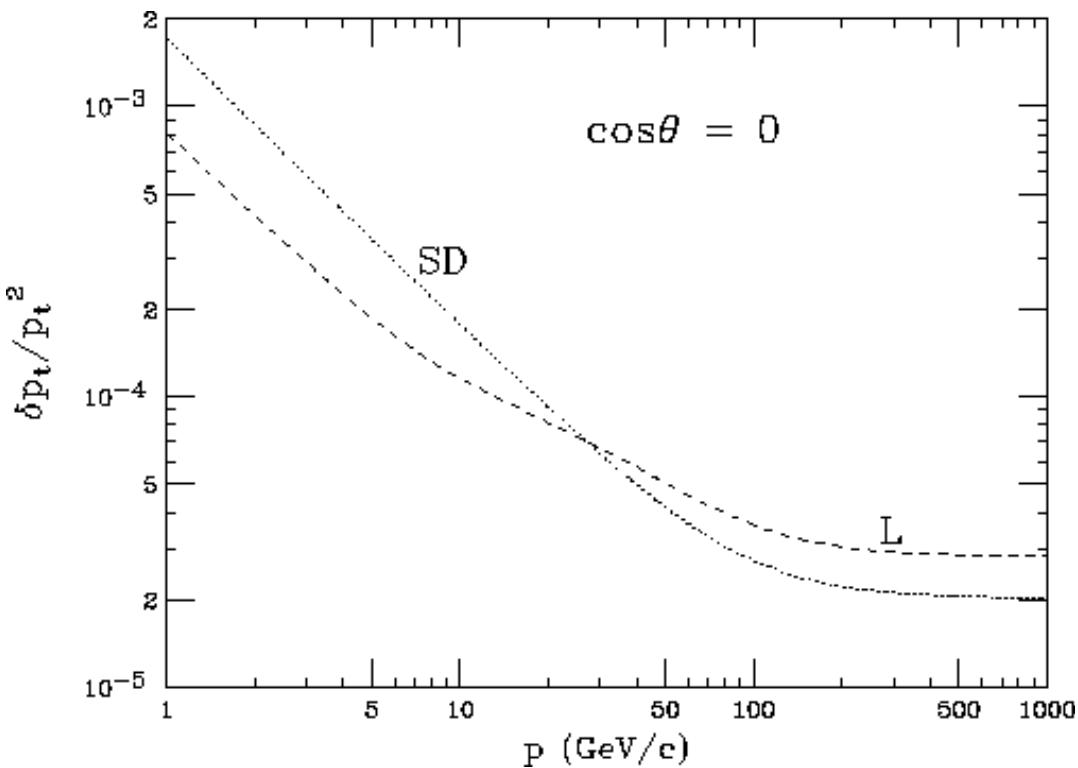


Bruce Schumm
SCIPP & UC Santa Cruz
SLAC LC Workshop
January 6-10, 2004

The SD Tracker

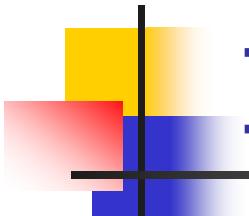


Tracker Performance



SD Detector burdened by material in five tracking layers (1.5% X_0 per layer) at low and intermediate momentum

Code: <http://www.slac.stanford.edu/~schumm/lcdtrk.tar.gz>



Idea: Noise vs. Shaping Time

Agilent 0.5 μm CMOS process (qualified by GLAST)

Min-i for 300 μm Si is about 24,000 electrons

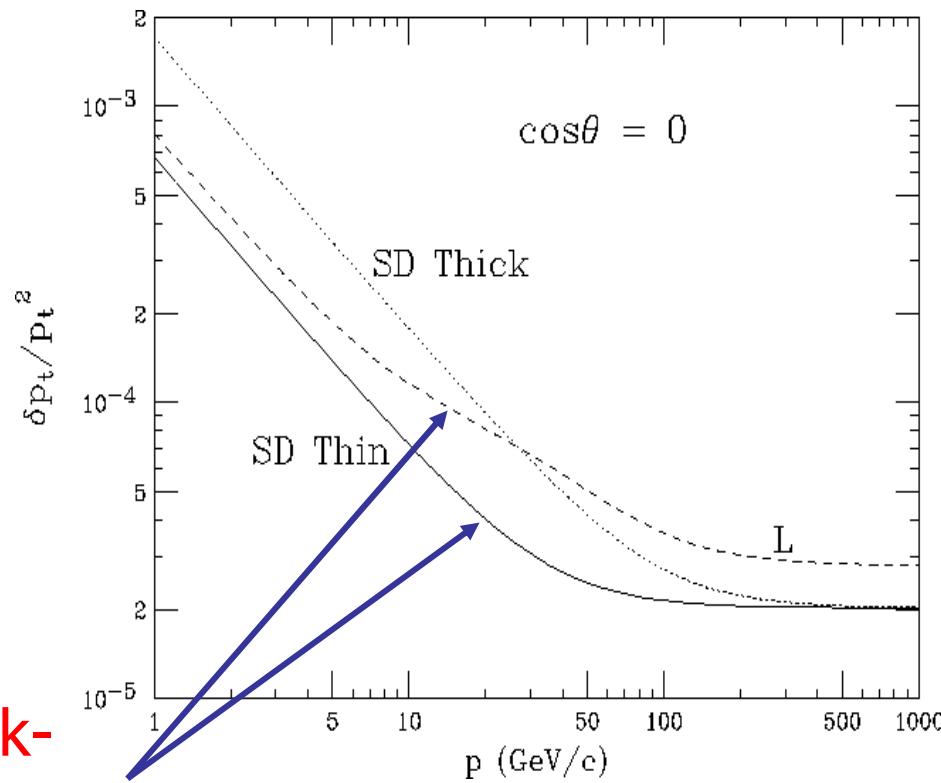
Shaping (μs)	Length (cm)	Noise (e^-)
1	100	2200
1	200	3950
3	100	1250
3	200	2200
10	100	1000
10	200	1850

The Gossamer Tracker

Ideas:

- Long ladders → substantially limit electronics readout and associated support
- Thin inner detector layers
- Exploit duty cycle → eliminate need for active cooling

→ Competitive with gaseous tracking over full range of momenta



Also: forward region...

TPC Material Burden

III-3

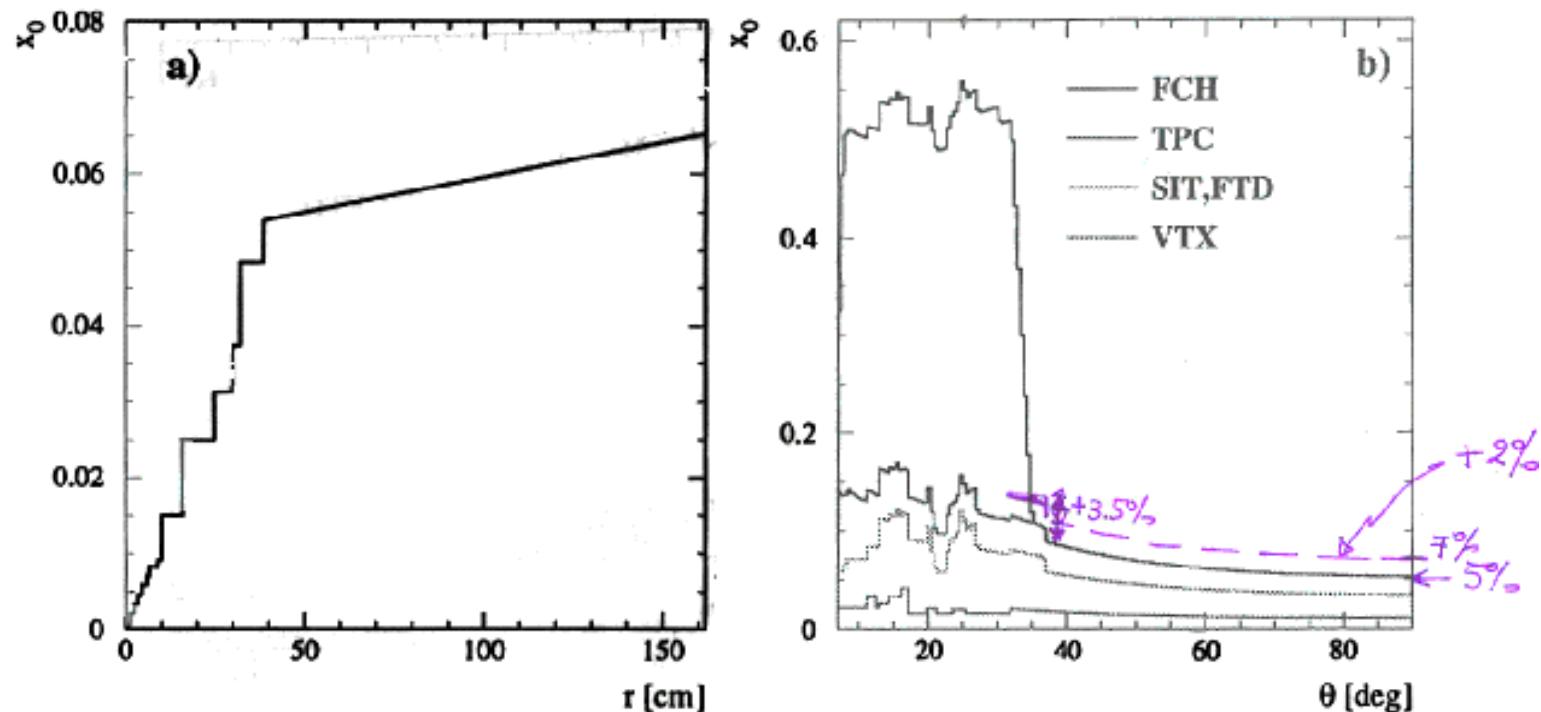
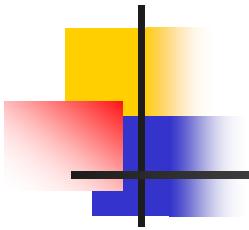


Figure 1.0.2: *Material distribution (a) as a function of the radius for $\theta = 90^\circ$ and (b) as a function of the polar angle up to the end of the different subdetectors. For the line labelled TPC the material up to the end of the sensitive volume is shown.*

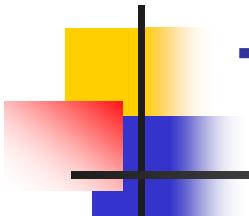


Pursuing the Long-Shaping Idea

LOCAL GROUP

SCIPP/UCSC

- Optimization of readout & sensors
 - Design & production of prototype ASIC
 - Development of prototype ladder; testing
- ➔ Supported by 2-year, \$95K grant from DOE Advanced Detector R&D Program



The SCIPP/UCSC Effort

Faculty/Senior

Alex Grillo
Hartmut Sadrozinski
Bruce Schumm
Abe Seiden

Post-Doc

Gavin Nesom
Jurgen Kroseberg

Student

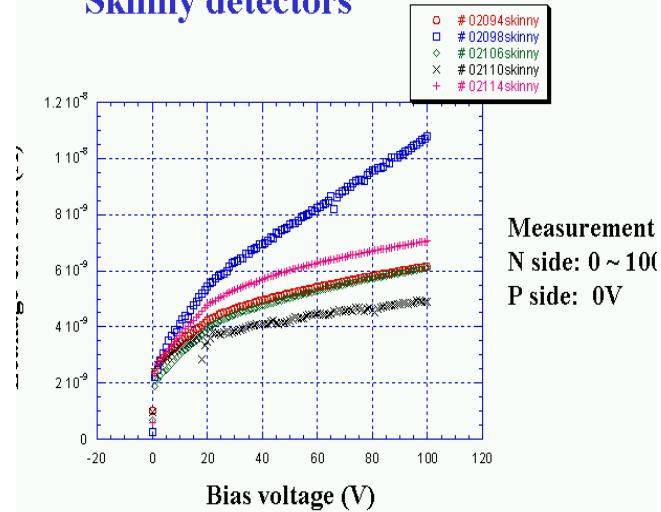
Christian Flacco
(will do BaBar
thesis)

Engineer: Ned Spencer (on SCIPP base program)

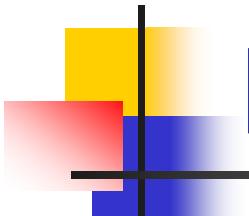
SCIPP/UCSC Development Work

Characterize GLAST `cut-out' detectors (8 channels with pitch of $\sim 200 \mu\text{m}$) for prototype ladder

Leakage current for five Skinny detectors



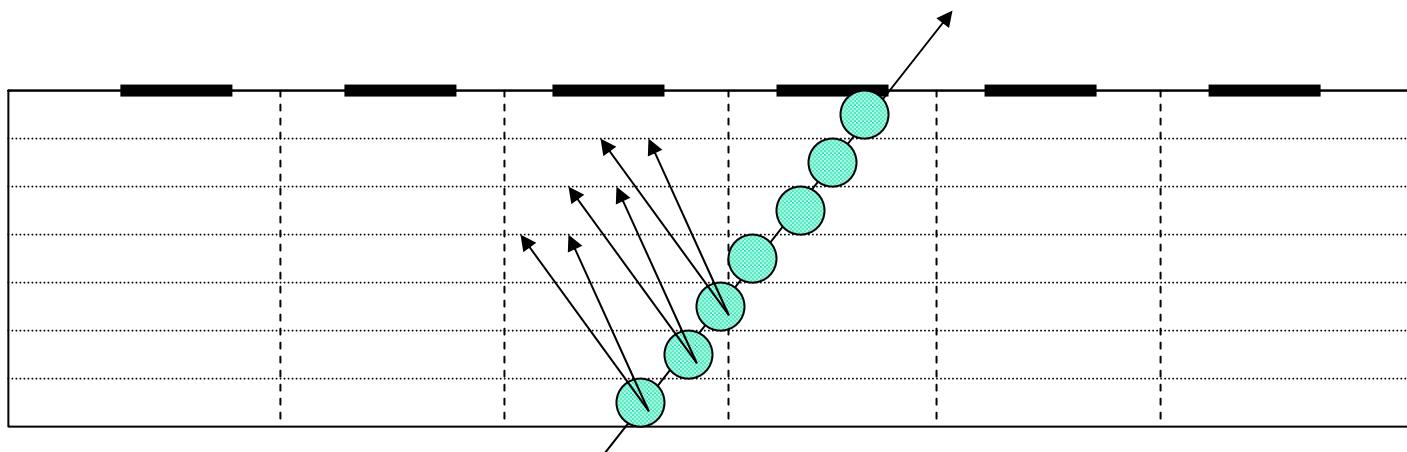
Detailed simulation of pulse development, electronics, and readout chain for optimization and to guide ASIC development (most of work so far)...



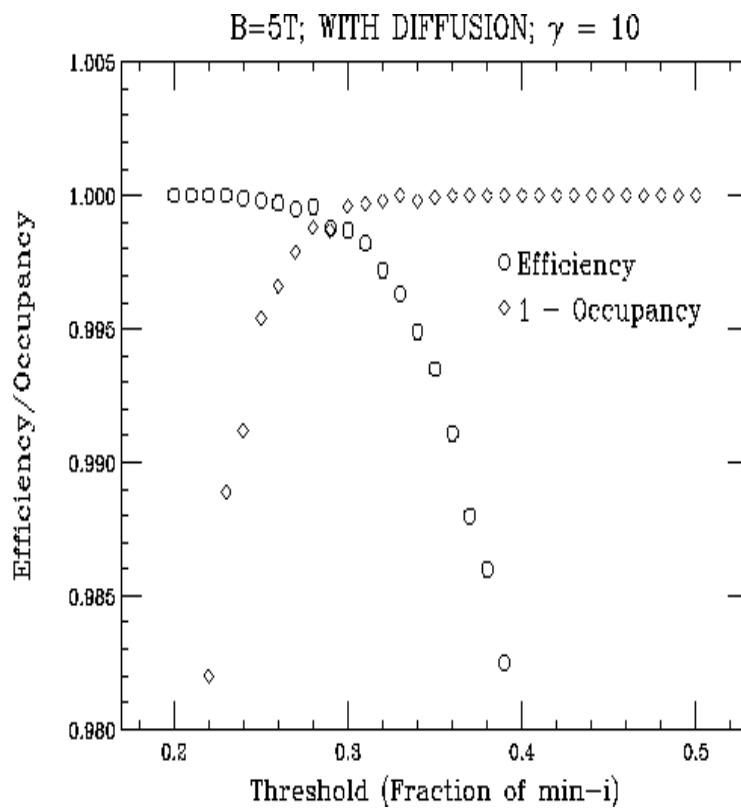
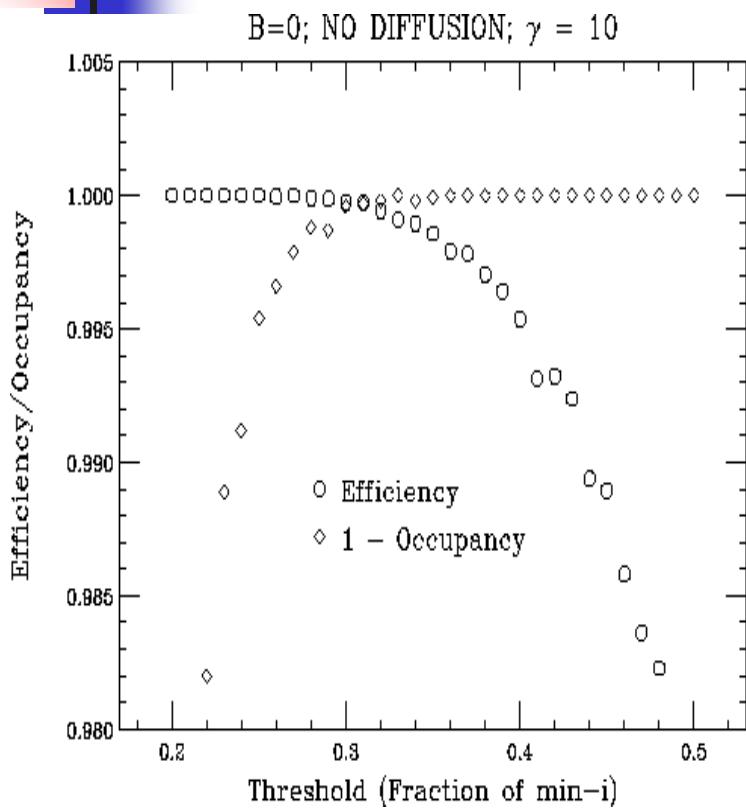
Pulse Development Simulation

Long Shaping-Time Limit: strip sees signal if and only if hole is collected onto strip (no electrostatic coupling to neighboring strips)

Incorporates: Landau statistics (SSSimSide; Gerry Lynch LBNL),
detector geometry and orientation, diffusion and space-charge,
Lorentz angle, electronic response



Result: S/N for 167cm Ladder



At shaping time of $3\mu\text{s}$; $0.5 \mu\text{m}$ process qualified by GLAST

Analog Readout Scheme: Time-Over Threshold (TOT)

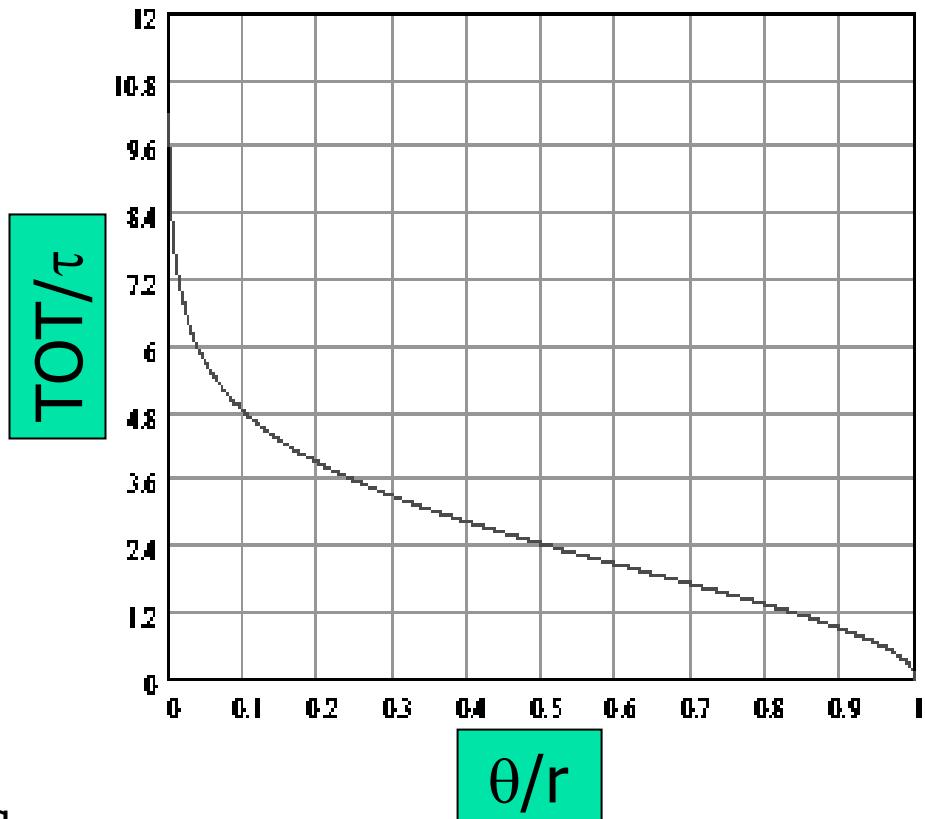
$$\theta = \frac{n_e^{\text{thresh}}}{\langle n_e \rangle_{\text{min-i}}} \quad r = \frac{n_e^{\text{pulse}}}{\langle n_e \rangle_{\text{min-i}}}$$

TOT given by difference between two solutions to

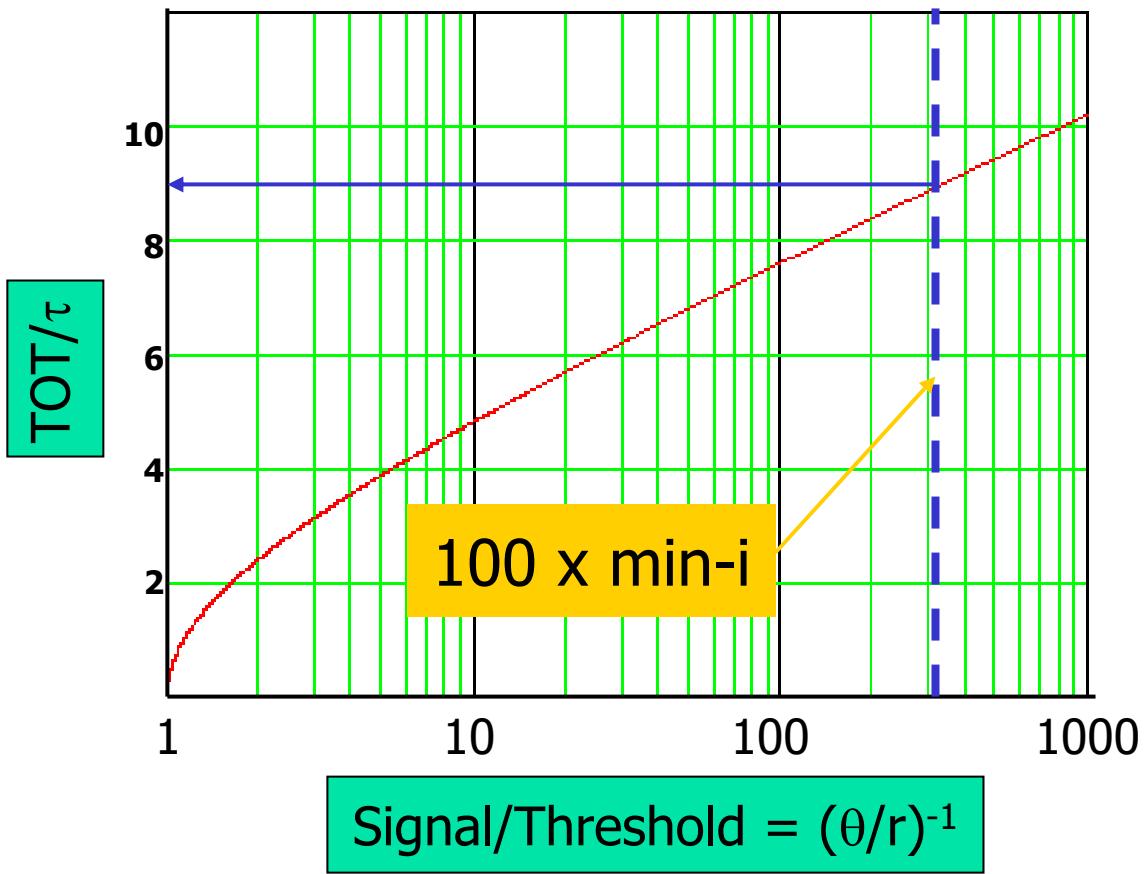
$$\frac{\theta}{r} = \frac{et}{\tau} e^{-t/\tau}$$

(RC-CR shaper)

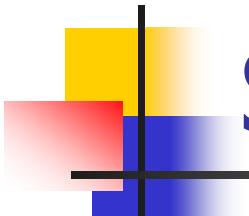
Digitize with granularity τ/n_{dig}



Why Time-Over-Threshold?



With TOT analog readout:
Live-time for 100x dynamic range is about 9τ
With $\tau = 3 \mu\text{s}$, this leads to a live-time of about $30 \mu\text{s}$, and a **duty cycle of about 1/250**
→ Sufficient for power-cycling!

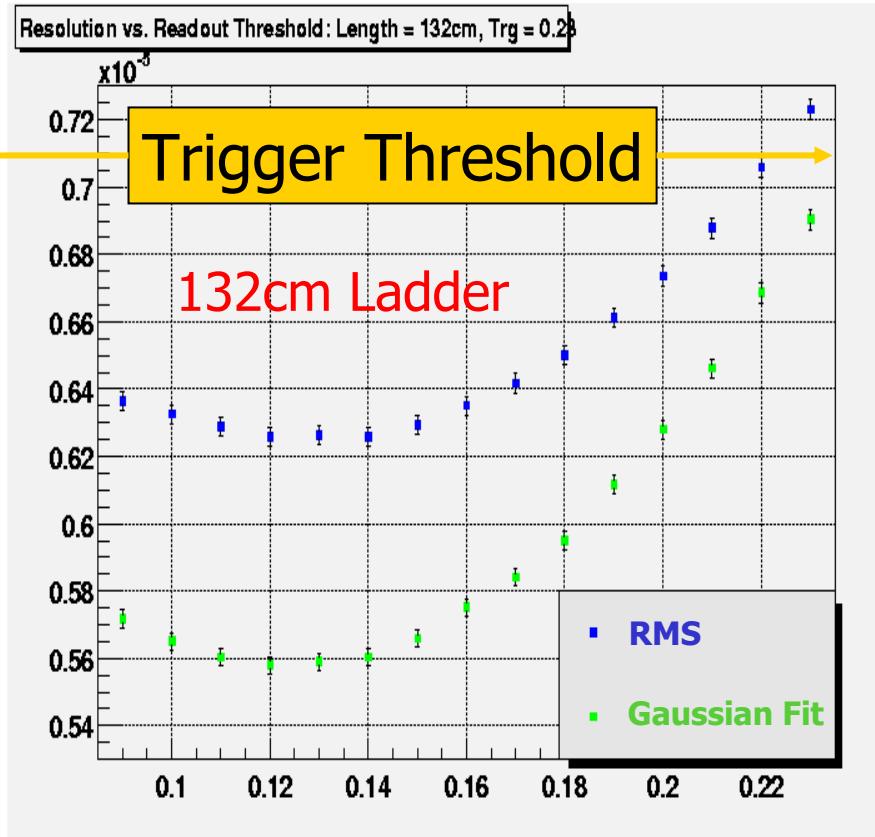
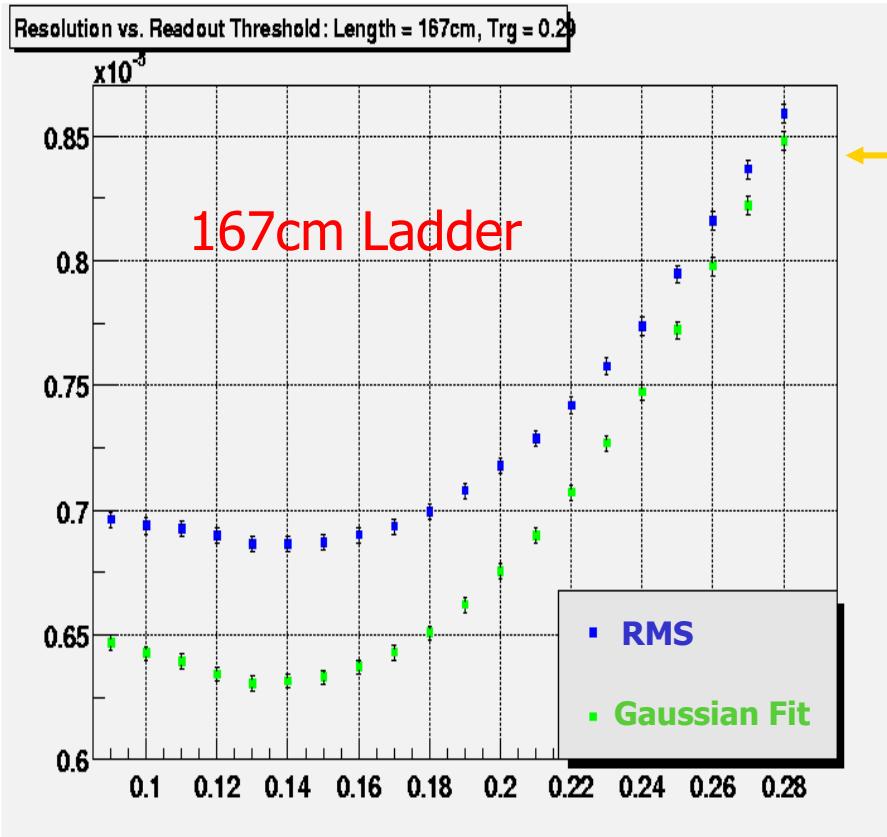


Single-Hit Resolution

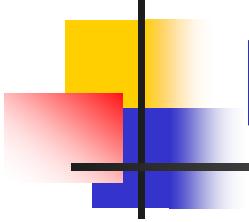
Design performance assumes $7\mu\text{m}$ single-hit resolution.
What can we really expect?

- Implement nearest-neighbor clustering algorithm
- Digitize time-over-threshold response ($0.1*\tau$
more than adequate to avoid degradation)
- Explore use of second `readout threshold' that is
set lower than `triggering threshold'; **major
design implication**

Resolution With and Without Second (Readout) Threshold



Readout Threshold (Fraction of min-i)

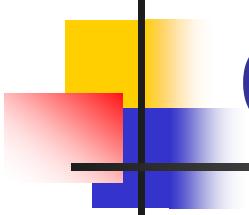


Lifestyle Choices

Based on simulation results, ASIC design will incorporate:

- 3 μ s shaping-time for preamplifier
- Time-over-threshold analog treatment
- Dual-discriminator architecture

The design of this ASIC is now underway.



Challenges

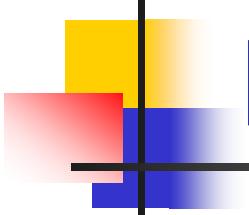
Cycling power quickly is major design challenge

Warm machine: At 120 Hz, must conduct business in ~150 μ s to achieve 98% power reduction

What happens when amplifier is switched off?

Drift of ~10 mV (or 1 fC in terms of charge) enough to fake signal when amp switched back on

Challenging for circuit design ('matching')



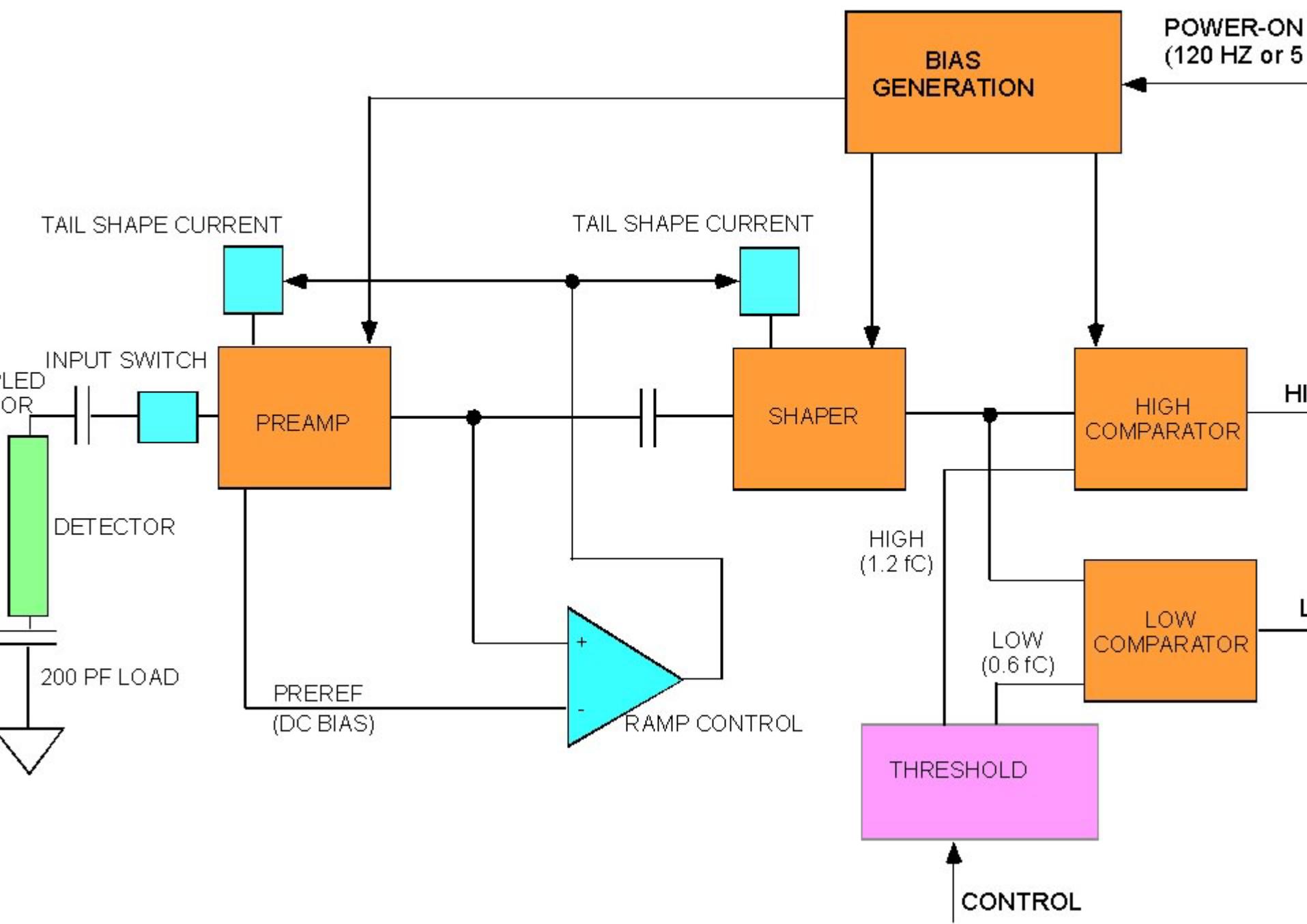
More Challenges

Trying to reach dynamic range of >100 MIP to allow for dEdX measurement of exotic heavy particles

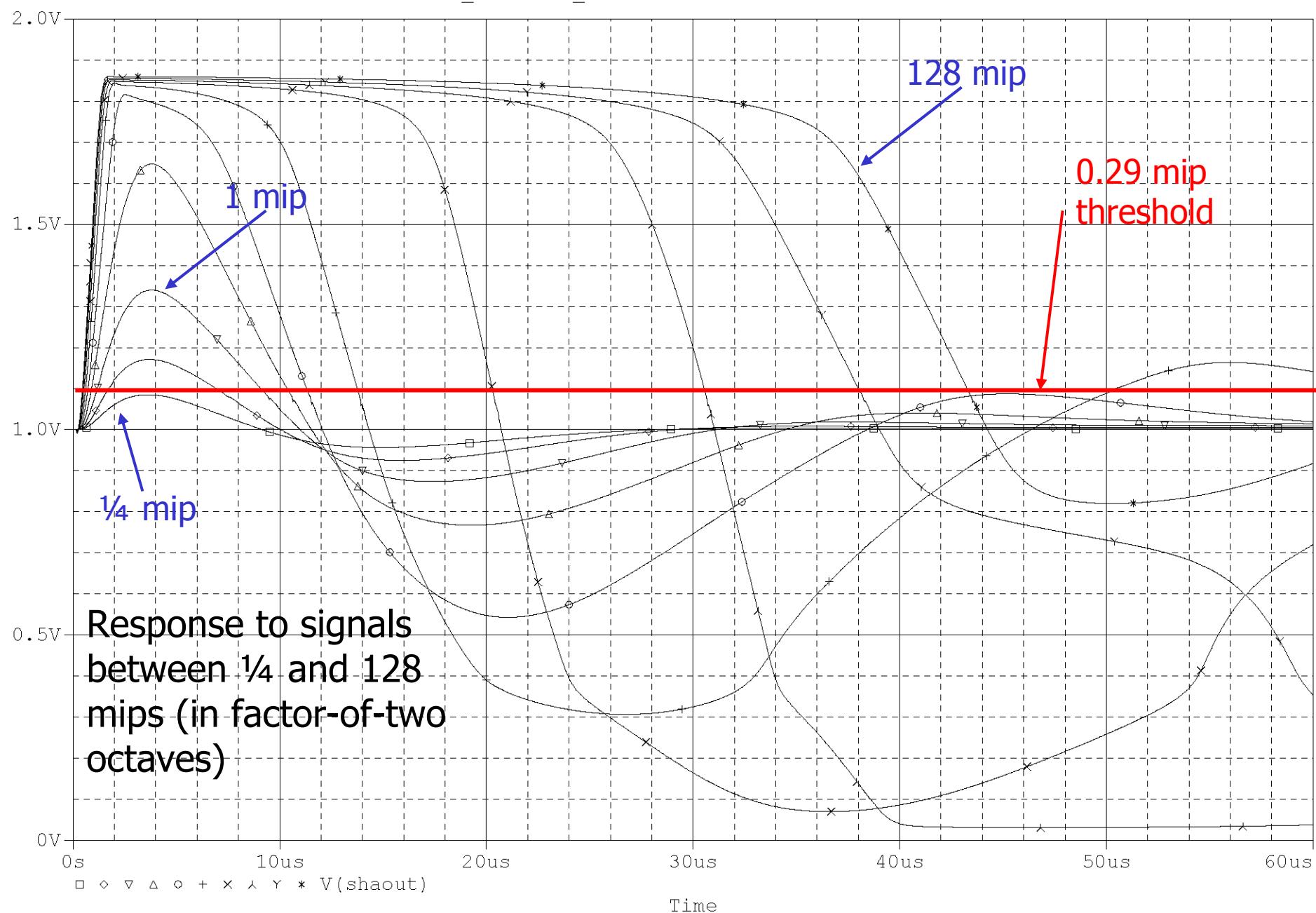
At comparitor, MIP is about 500 mV, rail is about 1V

→ Active 'Ramp Control' forces current back against signal for few MIP and greater.

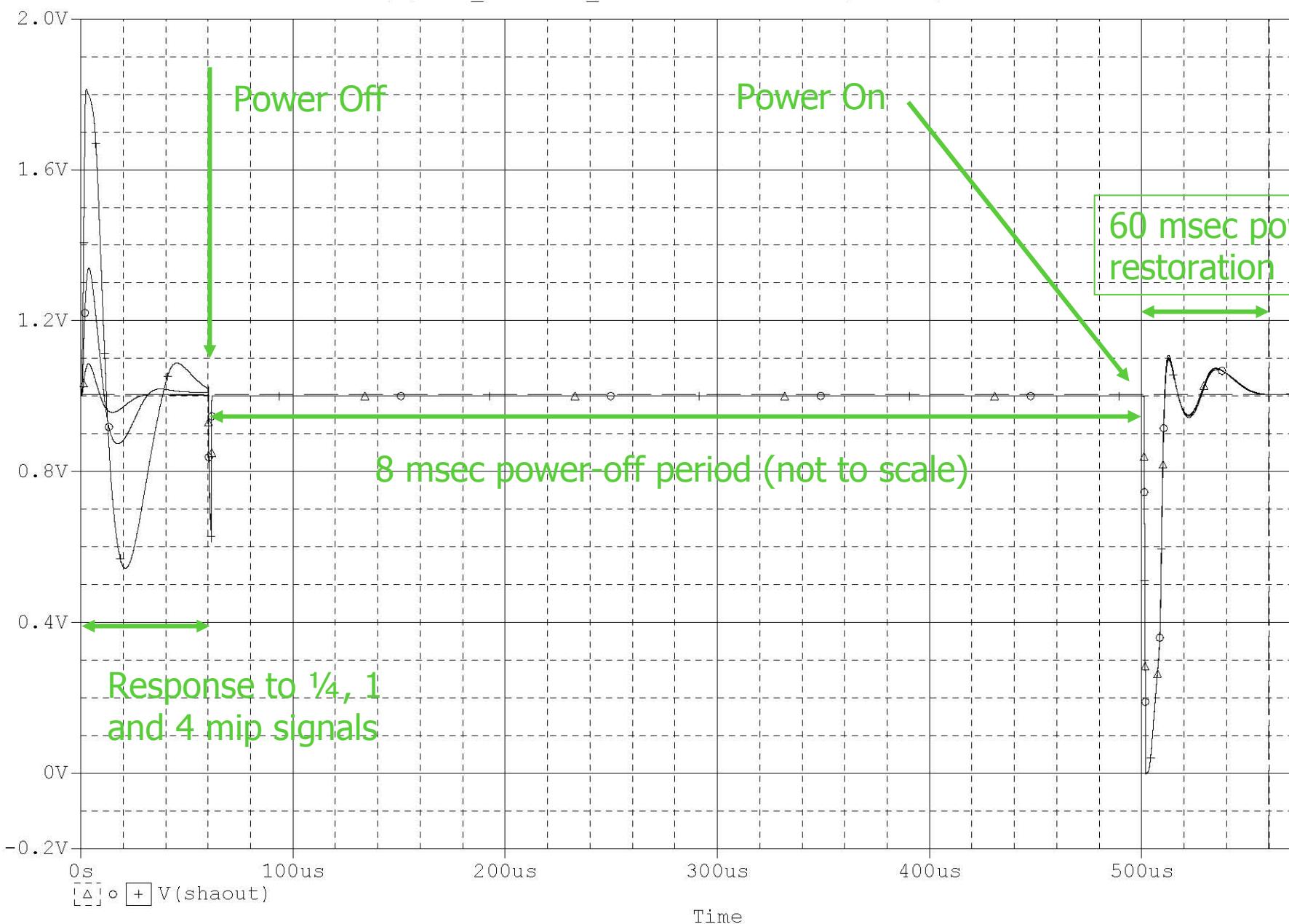
SILICON TRACKER FRONT-END ARCHITECTURE



(A) nlc Chan-nlc Chan-transient.dat (active)



(A) nlc_chan-nlc_chan-transient.dat (active)

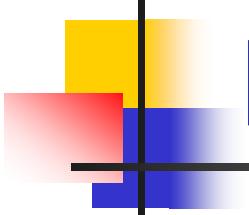


A1: (0.000, 1.0002) A2: (559.875u, 1.0038) DIFF(A) : (-559.875u, -3.6378m)

Date: January 02, 2004

Page 1

Time: 14:



Looking ahead

Challenges continue to arise in circuit design (but at least they're being caught before the chip is made!)

Layout in specific technology ($0.25\text{ }\mu\text{m}$ mixed-signal RF process from Taiwan Semiconductor) lies ahead; substantial experience at SLAC and within UCSC School of Engineering → Submit in March?

Long ladder, Nd:YAG pulsing system, readout under development

Project is very challenging, but progress is being made, albeit slower than first envisioned.